

Global Semiconductor Wafer Back Grinding Equipment Market 2026 by Manufacturers, Regions, Type and Application, Forecast to 2032

<https://marketpublishers.com/r/G6F15EEA6C81EN.html>

Date: July 2026

Pages: 120

Price: US\$ 3,480.00 (Single User License)

ID: G6F15EEA6C81EN

Abstracts

According to our (Global Info Research) latest study, the global Semiconductor Wafer Back Grinding Equipment market size was valued at US\$ 1605 million in 2025 and is forecast to a readjusted size of US\$ 2428 million by 2032 with a CAGR of 6.1% during review period.

Semiconductor Wafer Back Grinding Equipment refers to precision semiconductor manufacturing equipment used to thin wafers from the backside after front-end processing. The process involves mechanical grinding, polishing, and stress relief techniques to reduce wafer thickness and enable ultra-thin wafers required for advanced packaging and high-performance semiconductor devices. It is widely used in wafer-level packaging, 3D IC integration, memory devices, image sensors, power semiconductors, and advanced logic chips. The equipment typically includes grinding wheels, wafer chuck systems, cooling and slurry systems, thickness measurement modules, and automated control units. The industrial chain of Semiconductor Wafer Back Grinding Equipment includes upstream components such as diamond grinding wheels, abrasives, polishing pads, wafer chucks, motion control systems, sensors, cooling and filtration systems, and control software. The midstream consists of equipment design, wafer thinning process development, stress optimization, surface damage control, automation integration, metrology calibration, system installation, and maintenance services. Downstream applications include semiconductor fabs, advanced packaging facilities, memory manufacturers, image sensor producers, power semiconductor companies, and 3D IC integration processes. The industry requires ultra-high precision, wafer uniformity, surface integrity control, and low defect density. In 2025, global Semiconductor Wafer Back Grinding Equipment production reached approximately 3,714 units, with an average global market price of around US\$420,000.

per unit. The gross profit margin of major companies in the industry is between 30% ? 50%. In 2025, the global production capacity of Semiconductor Wafer Back Grinding Equipment was approximately 4,952 units.

The Semiconductor Wafer Back Grinding Equipment market is driven by increasing demand for ultra-thin wafers in advanced semiconductor packaging and device miniaturization. As chip architectures evolve toward higher integration density, 3D IC structures, and heterogeneous integration, wafer thinning has become a critical process step. Back grinding improves electrical performance, reduces device thickness, and enhances thermal management. The market is strongly supported by applications in memory devices, image sensors, power semiconductors, and advanced logic chips. Key technology trends include ultra-precision grinding, low-stress thinning, in-situ metrology, and fully automated wafer handling systems. However, challenges such as wafer cracking, surface damage control, and yield stability remain. Overall, the market is expected to grow steadily with the expansion of advanced packaging and semiconductor scaling technologies.

This report is a detailed and comprehensive analysis for global Semiconductor Wafer Back Grinding Equipment market. Both quantitative and qualitative analyses are presented by manufacturers, by region & country, by Type and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

Key Features:

Global Semiconductor Wafer Back Grinding Equipment market size and forecasts, in consumption value (\$ Million), sales quantity (Units), and average selling prices (K US\$/Unit), 2021-2032

Global Semiconductor Wafer Back Grinding Equipment market size and forecasts by region and country, in consumption value (\$ Million), sales quantity (Units), and average selling prices (K US\$/Unit), 2021-2032

Global Semiconductor Wafer Back Grinding Equipment market size and forecasts, by Type and by Application, in consumption value (\$ Million), sales quantity (Units), and average selling prices (K US\$/Unit), 2021-2032

Global Semiconductor Wafer Back Grinding Equipment market shares of main players, shipments in revenue (\$ Million), sales quantity (Units), and ASP (K US\$/Unit), 2021-2026

The Primary Objectives in This Report Are:

To determine the size of the total market opportunity of global and key countries

To assess the growth potential for Semiconductor Wafer Back Grinding Equipment

To forecast future growth in each product and end-use market

To assess competitive factors affecting the marketplace

This report profiles key players in the global Semiconductor Wafer Back Grinding Equipment market based on the following parameters - company overview, sales quantity, revenue, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include DISCO Corporation, ACCRETECH Tokyo Seimitsu Co., Ltd., Okamoto Machine Tool Works, Ltd., Revasum, Inc., Komatsu NTC Ltd., JTEKT Machinery Americas Corporation, Lapmaster Wolters GmbH, G&N Genauigkeits Maschinenbau N?rnberg GmbH, Engis Corporation, Logitech Ltd., etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market Segmentation

Semiconductor Wafer Back Grinding Equipment market is split by Type and by Application. For the period 2021-2032, the growth among segments provides accurate calculations and forecasts for consumption value by Type, and by Application in terms of volume and value. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Type

Coarse Back Grinding Equipment

Fine Back Grinding Equipment

Ultra-fine Back Grinding Equipment

Market segment by Equipment Automation Level

Manual Wafer Back Grinding Equipment

Semi-Automatic Wafer Back Grinding Equipment

Fully Automatic Wafer Back Grinding Equipment

Market segment by Wafer Diameter

Up to 200 mm Wafer Diameter

Above 200 mm to 300 mm Wafer Diameter

Above 300 mm Wafer Diameter

Market segment by Application

Advanced Packaging Wafer Thinning

Power Semiconductor Wafer Thinning

MEMS and Sensor Wafer Thinning

Compound Semiconductor Wafer Thinning

Major players covered

DISCO Corporation

ACCRETECH Tokyo Seimitsu Co., Ltd.

Okamoto Machine Tool Works, Ltd.

Revasum, Inc.

Komatsu NTC Ltd.

JTEKT Machinery Americas Corporation

Lapmaster Wolters GmbH

G&N Genauigkeits Maschinenbau Nürnberg GmbH

Engis Corporation

Logitech Ltd.

Beijing CETC Electronic Equipment Group Co., Ltd.

Hwatsing Technology Co., Ltd.

Market segment by region, regional analysis covers

North America (United States, Canada, and Mexico)

Europe (Germany, France, United Kingdom, Russia, Italy, and Rest of Europe)

Asia-Pacific (China, Japan, Korea, India, Southeast Asia, and Australia)

South America (Brazil, Argentina, Colombia, and Rest of South America)

Middle East & Africa (Saudi Arabia, UAE, Egypt, South Africa, and Rest of Middle East & Africa)

The content of the study subjects, includes a total of 15 chapters:

Chapter 1, to describe Semiconductor Wafer Back Grinding Equipment product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top manufacturers of Semiconductor Wafer Back Grinding Equipment, with price, sales quantity, revenue, and global market share of Semiconductor Wafer Back Grinding Equipment from 2021 to 2026.

Chapter 3, the Semiconductor Wafer Back Grinding Equipment competitive situation, sales quantity, revenue, and global market share of top manufacturers are analyzed emphatically by landscape contrast.

Chapter 4, the Semiconductor Wafer Back Grinding Equipment breakdown data are shown at the regional level, to show the sales quantity, consumption value, and growth by regions, from 2021 to 2032.

Chapter 5 and 6, to segment the sales by Type and by Application, with sales market share and growth rate by Type, by Application, from 2021 to 2032.

Chapter 7, 8, 9, 10 and 11, to break the sales data at the country level, with sales quantity, consumption value, and market share for key countries in the world, from 2021 to 2026. and Semiconductor Wafer Back Grinding Equipment market forecast, by regions, by Type, and by Application, with sales and revenue, from 2027 to 2032.

Chapter 12, market dynamics, drivers, restraints, trends, and Porters Five Forces analysis.

Chapter 13, the key raw materials and key suppliers, and industry chain of Semiconductor Wafer Back Grinding Equipment.

Chapter 14 and 15, to describe Semiconductor Wafer Back Grinding Equipment sales channel, distributors, customers, research findings and conclusion.

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